

PRODUCT SPECIFICATION **FOR LCD MODULE**

Revision: 1.0

Model No: LS016I01-MP-V1

Module Type: COG+FPC+B/L

APPROVED SIGNATURE

- ☒ Approved Product Specification only
- ☐ Approved Product Specification and Samples

<u>Prepared By</u>	<u>Checked By</u>	<u>Approved By</u>

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1. General Description

LS016I01-MP-V1 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 1.6 inch and the resolution is 400(RGB)*400, the panel can display up to 16M colors.

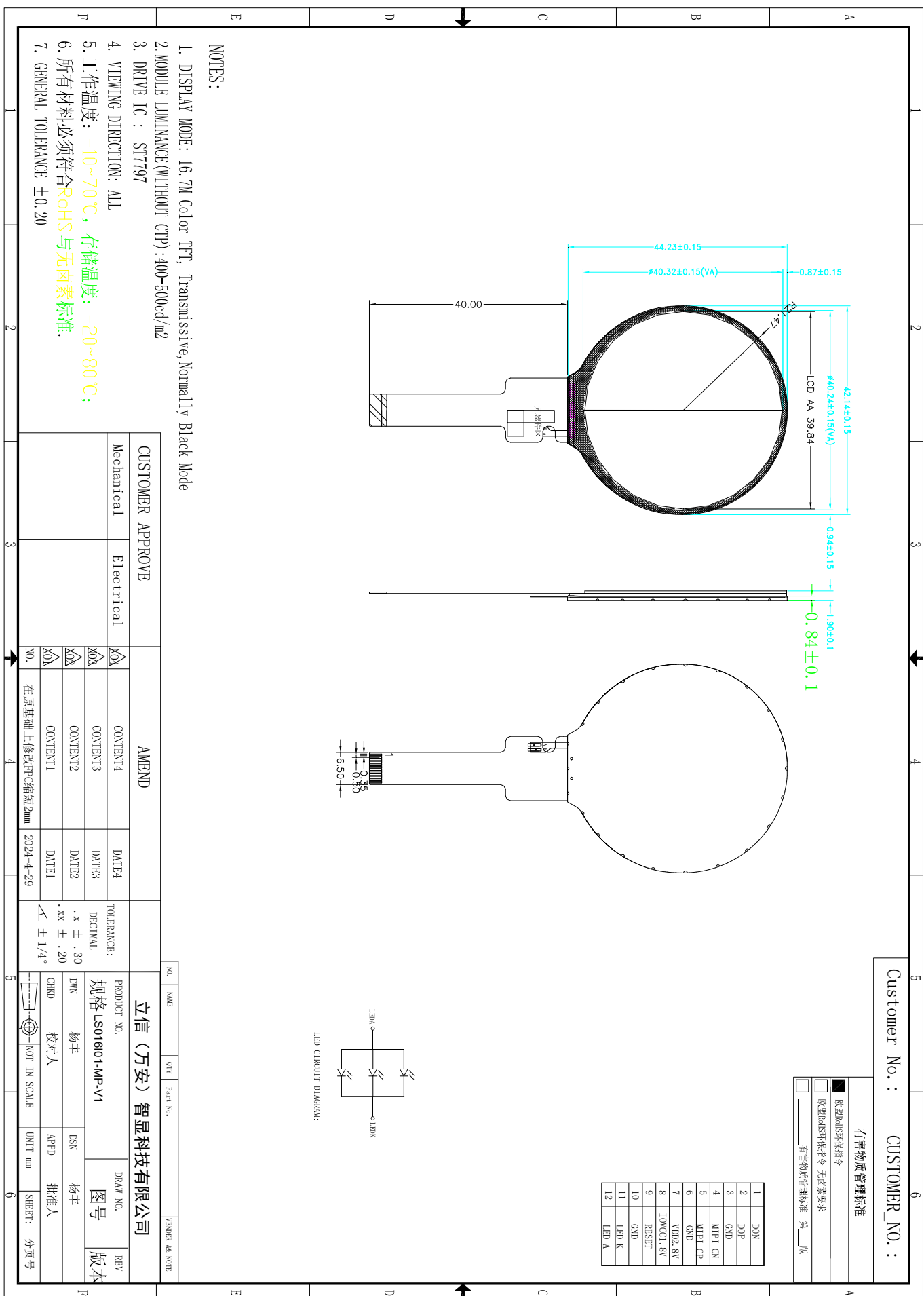
2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 400(RGB)×400 Dot-matrix
Input Data	MIPI input
Viewing Direction (Grayscale Inversion)	Free (IPS)
Drive	ST7797

3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	42.14 ×44.23×1.9	mm
Number of dots	400(RGB) ×400	pixel
Active area (H×V)	39.84×39.84	mm

4. Outline Dimension



5. Absolute Maximum Ratings

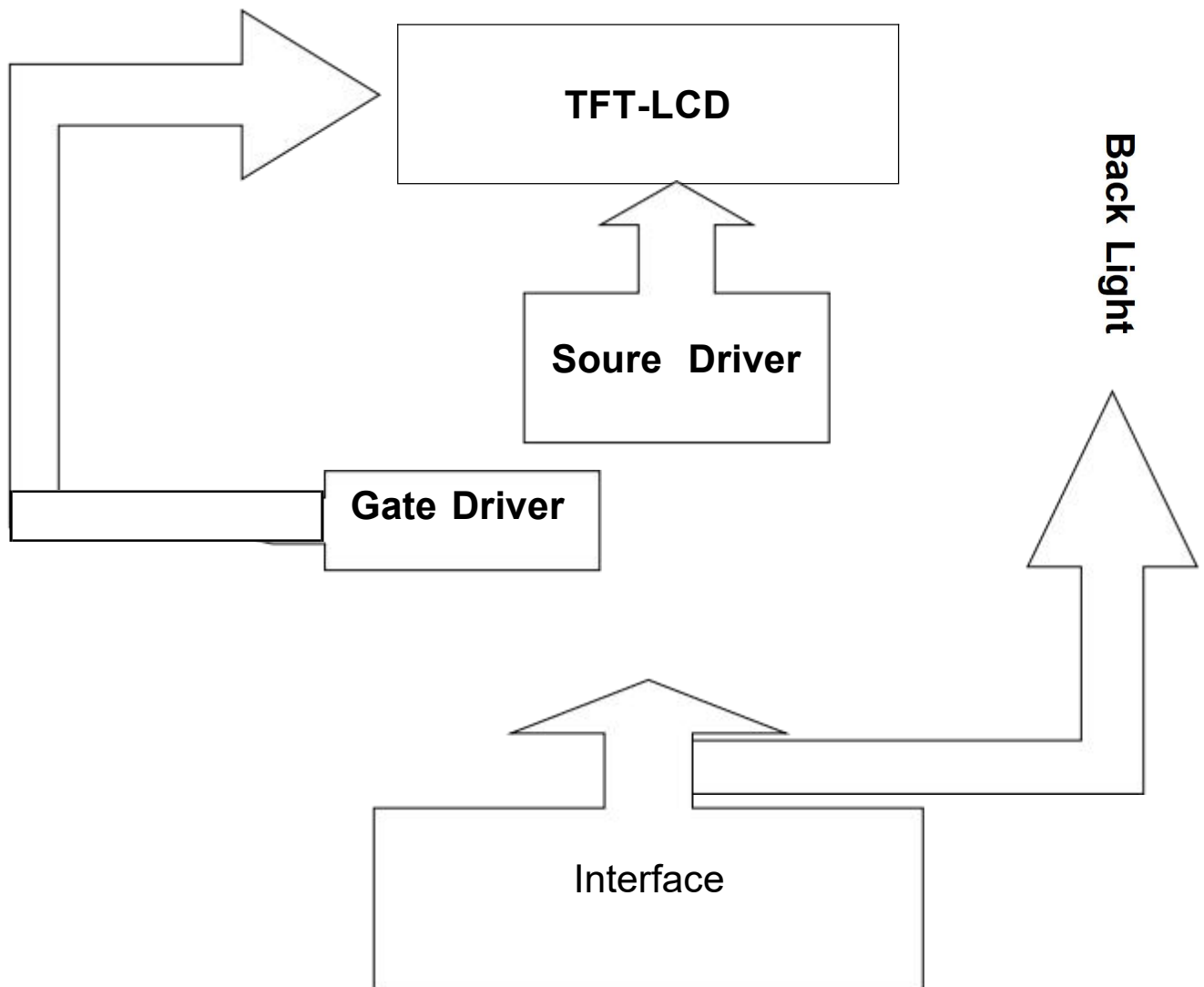
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VCC	-0.3	4.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	4.6	V	
Operating temperature	TOPR	-10	70	°C	
Storage temperature	TSTR	-20	80	°C	

6. Electrical Characteristics

Item		Symbol	Rating			Unit	Remark
			Min	Typ	Max		
Supply voltage		VCC	2.6	2.75	3.3	V	Note1
Supply voltage		IOVCC	1.65	1.8	3.3	V	
Input Voltage	L level	VIL	VSS	---	0.3*IOVCC	V	
	H level	VIH	0.7*IOVCC	---	IOVCC	V	

7. Module Function Description

7- 1. Block Diagram Of LCM



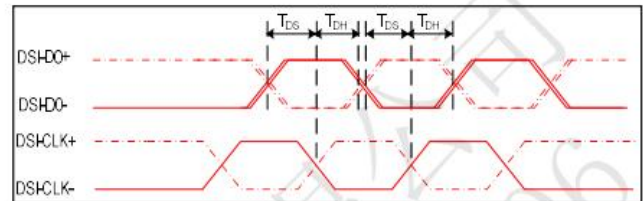
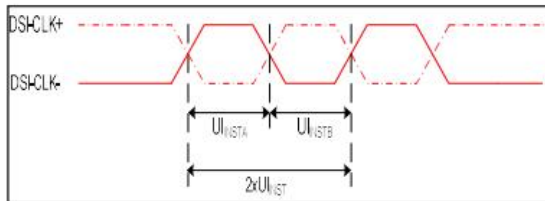
7-2. Pin Description

PIN NO.	Symbol	I/O	Description
1	D0N		Negative MIPI differential data inputs
2	D0P		Negative MIPI differential data inputs
3	GND		GND
4	MIPI_CN		Negative MIPI differential clock inputs
5	MIPI_CP		Negative MIPI differential clock inputs
6	GND		GND
7	VDD2.8V		Power voltage
8	IOVCC1.8V		Power voltage
9	RESET		Global reset pin
10	GND		GND
11	LED_K		Power for LED backlight cathode
12	LED_A		Power for LED backlight anode

7-3 Timing Characteristics

7.3.1.High Speed Mode

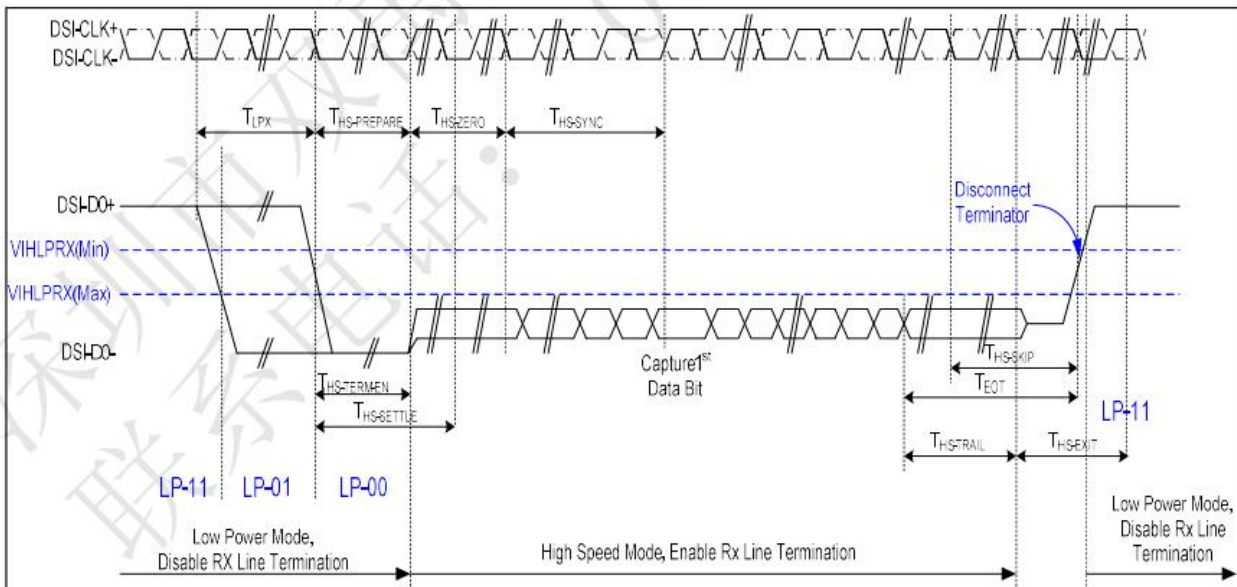
● Clock Channel Timing



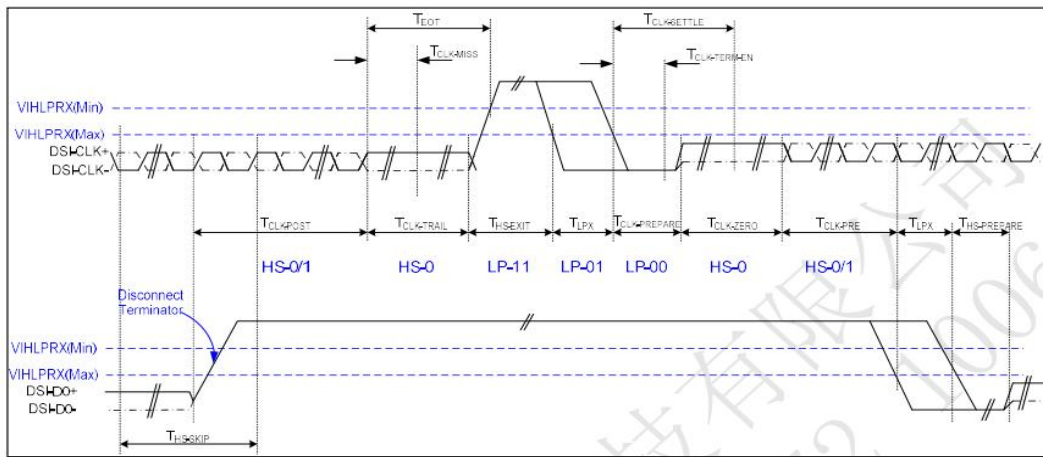
● Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	$2xUI_{INSTA}$	Double UI instantaneous	4	25	ns	-
DSI-CLK+/-	UI_{INSTA} UI_{INSTB}	UI instantaneous halves	2	12.5	ns	$UI = UI_{INSTA} = UI_{INSTB}$
DSI-Dn+/-	tDS	Data to clock setup time	0.15	-	UI	-
DSI-Dn+/-	tDH	Data to clock hold time	0.15	-	UI	-

● Data Transmission



Data lanes-Low Power Mode to/from High Speed Mode Timing

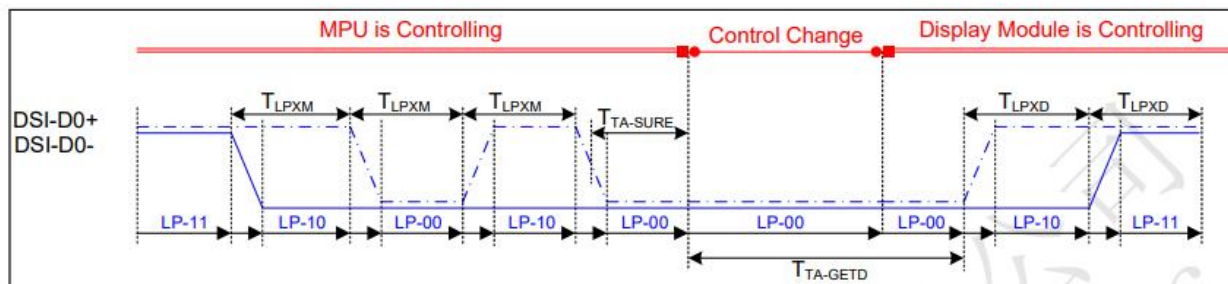


Clock lanes- High Speed Mode to/from Low Power Mode Timing

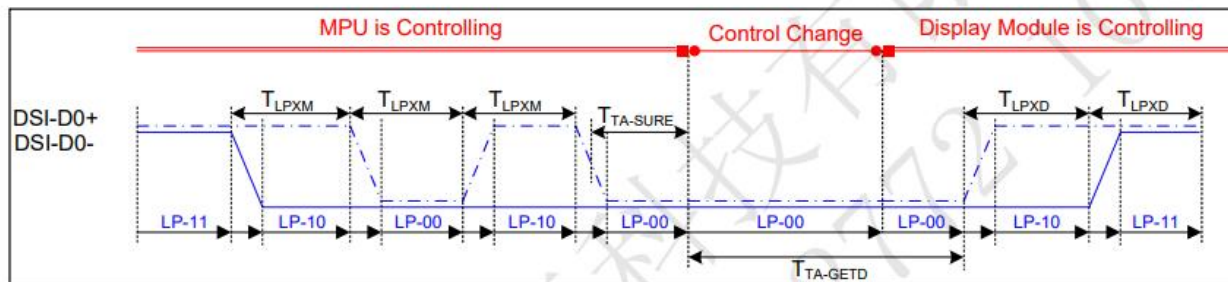
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
Low Power Mode to High Speed Mode Timing						
DSI-Dn+/-	TLPX	Length of any low power state period	50	-	ns	Input
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare for HS transmission	40+4UI	85+6UI	ns	Input
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from when Dn crosses VILMAX	-	35+4UI	ns	Input
DSI-Dn+/-	THS-PREPARE + THS-ZERO	THS-PREPARE + time to drive HS-0 before the sync sequence	140+10UI	-	ns	Input
High Speed Mode to Low Power Mode Timing						
DSI-Dn+/-	THS-SKIP	Time-out at display module to ignore transition period of EoT	40	55+4UI	ns	Input
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-Dn+/-	THS-TRAIL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4UI	-	ns	Input
High Speed Mode to/from Low Power Mode Timing						
DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode	60+52UI	-	ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for HS transmission	38	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time-out at clock lan display module to enable HS transmission	--	38	ns	Input
DSI-CLK+/-	TCLK-PREPARE + TCLK-ZERO	Minimum lead HS-0 drive period before starting clock	300	-	ns	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8UI	-	ns	Input
DSI-CLK+/-	TEOT	Time form start of TCLK-TRAIL period to start of LP-11 state	-	105ns+12UI	ns	Input

Mipi Interface- High Speed Mode Timing Characteristics

7.3.2.Low Power Mode



Bus Turnaround (BTA) from display module to MPU Timing



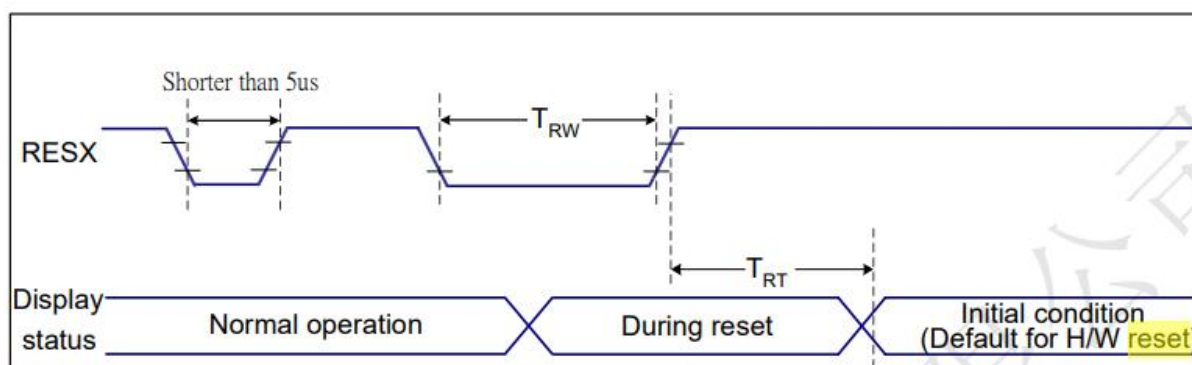
Bus Turnaround (BTA) from MPU to display module Timing

VDDI=1.8V, VCI=2.8V, AGND=DGND=AGNDR=0V, $T_a=25^{\circ}\text{C}$

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-D0+/-	TLPXM	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Input
DSI-D0+/-	TLPXD	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Output
DSI-D0+/-	TTA-SURED	Time-out before the MPU start driving	T_{LPXD}	$2 \times T_{LPXD}$	ns	Output
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by display module	$5 \times T_{LPXD}$		ns	Input
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after turnaround request-MPU	$4 \times T_{LPXD}$		ns	Output

MIPI Interface BTA Mode Timing Characteristics

7.3.3.Reset Timing

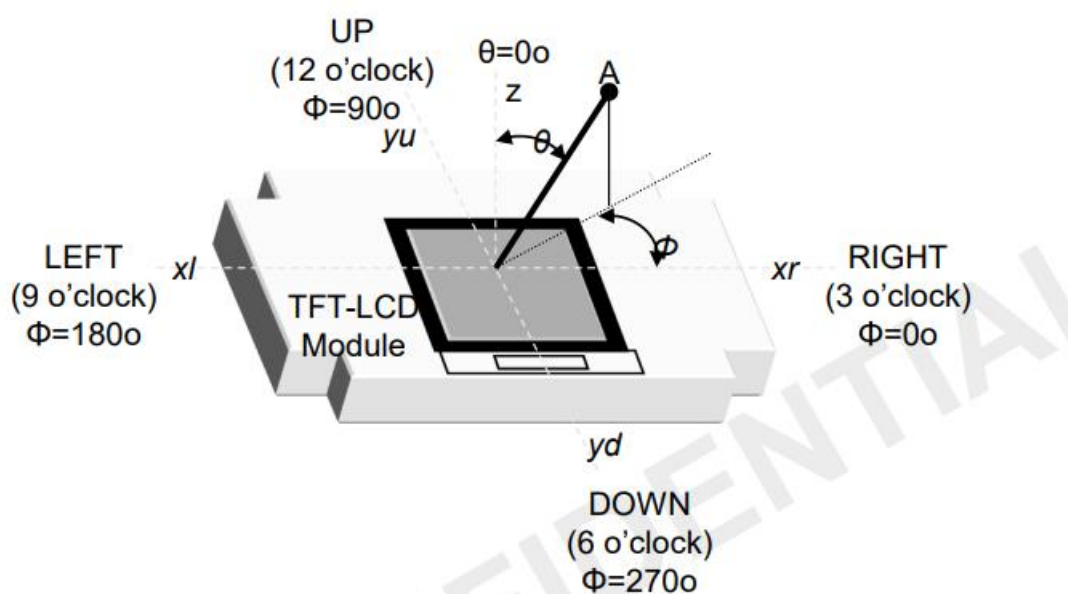


$V_{DDI}=1.8V, V_{CI}=2.8V, AGND=DGND=AGNDR=0V, T_a=25^{\circ}C$

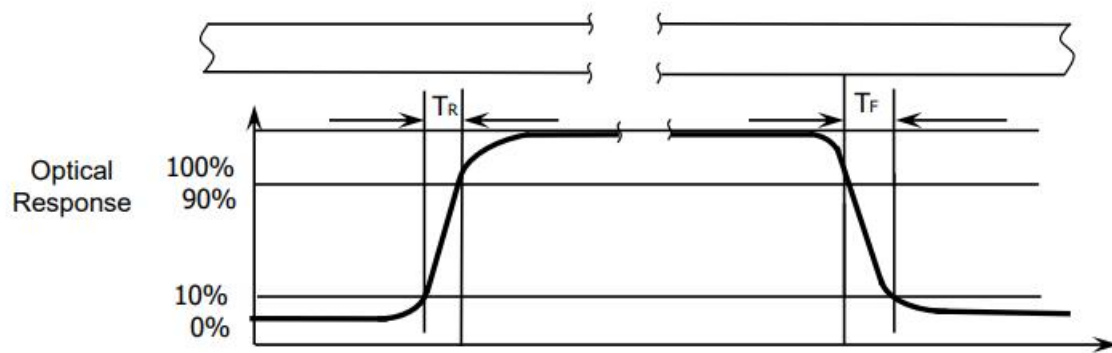
Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
			-	120 (Note 1, 6, 7)	ms

8. Electro-Optical Characteristics

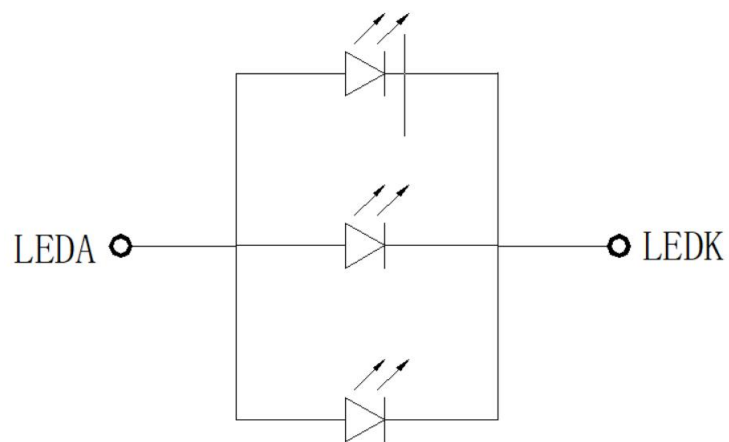
Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr +Tf	$\theta_x = \theta_y = 0$	---	25	35	ms	Note 1
Contrast Ratio		CR		900	1200	---	---	Note 2
Transmittance		T%		3.4	4.0	---	%	
Color Chromaticity (CIE1931)	White	W x	$\theta_x = \theta_y = 0$	---	0.294	---	---	
		W y		---	0.335	---	---	
Viewing angle	θ_T		CR > 10	---	85	---	Deg.	Note 3
	θ_B			---	85	---		
	θ_L			---	85	---		
	θ_R			---	85	---		
Luminance ($I_F = 60mA$)		L		400	---	500	cd/m2	Note4



$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$



Note(4) Backlight circuit



$I_F=60\text{mA}$ $V_F=2.8\text{V}\sim 3.3\text{V}$

9. Inspection Standards

1. AQL(Acceptable Quality Level)

AQL of major and minor defect

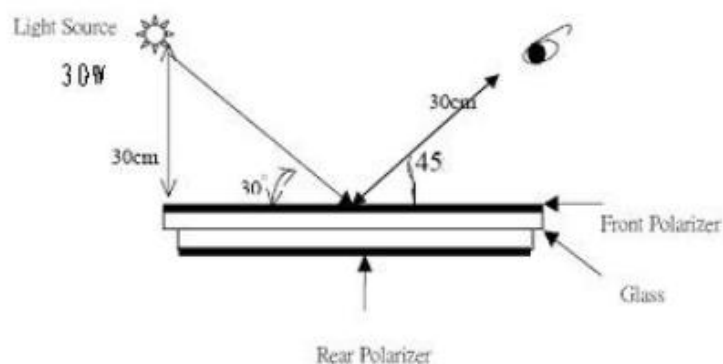
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINOR DEFECT
0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30°, a distance of 30cm with normal eye, with an angle of 45° degree to check the products without uncovering the film!

(As shown below)

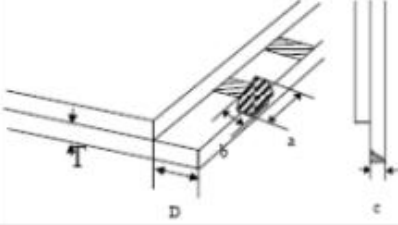
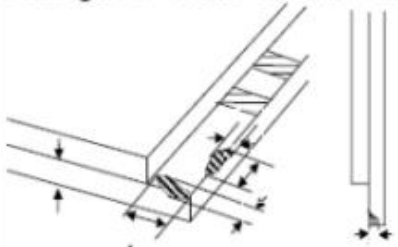


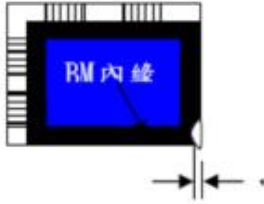
3. Inspection item and criteria

3.1 Visual inspection criterion in immobility

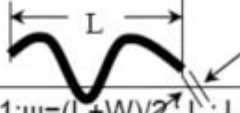
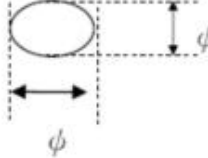
3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks (Major defect)	1.Linear cracks on panel 【 Reject】 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage 1) $b \leq 1/3$ Pin width(non bonding area) 【 Accept】 2) bonding area $\leq 0.5\text{mm}$ 【 Accept】	a:Length, b:Width
4	Pin-side , conductive area damaged (minor defect)	(a c : disregards) $b \leq 1/3$ of effective length for bonding electrode 【 Accept】	a : Length · b : Width · c : Thickness 
5	Pin-side , non-conductive area damaged (minor defect)	1) Damage area don't touch the ITO (Inclueing contraposition mark,except scribing mark) 【 Accept】 2) $c < T$ $b \leq BM$ 1/3 of width 【 Accept】 3) $c = T$ b not touch the seal glue 【 Accept】 4) a disregards	a : Length · b : Width · c : Thickness 

No	Defect item	Criteria	Remark
6	Non-pin-side damage (minor defect)	$c < T$	c : Thickness b: width of damage 
		1) b exceeds 1/3 BM	
		【Reject】	
		$c = T$ b not touch the seal glue	
		【Reject】	

3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber 、 glass cratch 、 polarizer scratch/folded (minor defect)	Specification	Allowable	note1: L : Length , W : Width note2: disregard if out of AA 
		$0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	
2	Polarizer bubble 、 concave and convex (minor defect)	$\psi \leq 0.2\text{mm}$	disregard	note 1: $\psi = (L+W)/2$; L : Length , W : Width note2: disregard if out of AA
		$0.2\text{mm} < \psi \leq 0.3\text{mm}$	2	
		$0.3\text{mm} < \psi \leq 0.5\text{mm}$	1	
		$0.5\text{mm} < \psi$	0	
3	Black dots 、 dirty dots 、 impurities 、 eyewinker (Major defect)	$\psi \leq 0.15\text{mm}$	disregard	note2: disregard if out of AA 
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
4	Polarizer prick (Major defect)	$\psi \leq 0.1\text{mm}$	disregard	note1: $\psi = (L+W)/2$; L = Length , W = Width note2: the distance between two dots > 5mm
		$0.1\text{mm} < \psi \leq 0.25\text{mm}$	3	
		$\psi > 0.25\text{mm}$	0	

3.1.3 .FPC

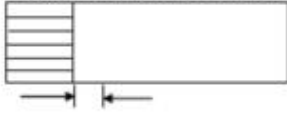
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【 Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【 Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		$\psi \leq 0.25\text{mm}$	2	
		$\psi > 0.25$	0	

3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift (minor defect)	1.shift spec: 1)glue to the polarize 【 Reject】 2) IC bare 【 Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【 Reject】 2)IC bare 【 Reject】	
2	No black tape (Major defect)	No black tape 【 Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【 Reject】	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film. 【 Reject】	

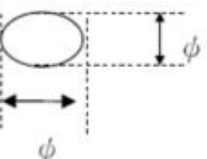
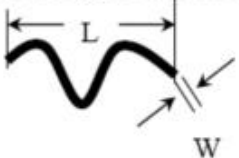
3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【 Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area 【 Reject 】 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) 【 accept 】	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer 【 Reject 】	Except of the special requirement .

3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display 【 Reject 】	
2	Missing line (Major defect)	Missing line 【 Reject 】	
3	Seg-com light and dark (Major defect)	Seg-com light and dark 【 Reject 】	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility 【 Reject 】	
5	Flicker of Pattern (Major defect)	Flicker of Pattern 【 Reject 】	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current 【 Reject 】	
8	Voltage out of specification (Major defect)	Voltage out of specification 【 Reject 】	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code 【 Reject 】	
10	Dark light, Flicker (Major defect)	Dark light, Flicker 【 Reject 】	

No	Defect item	Criteria	Remark	
11	Black/White dots · Dirty dots · eyewinker (Major defect)	Specification	Allowable	Note1: disregard if out of AA 
		$\psi \leq 0.15\text{mm}$	disregard	
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
12	Fiber · glass cratch · polarizer scratch/folded (minor defect)	$W \leq 0.03\text{mm}$	disregard	note1: L : Length · W : Width note2: disregard if out of AA 
		$0.03\text{mm} < W \leq 0.05\text{mm} ;$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm} ;$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm} ; L > 3.0\text{mm}$	0	

10.Records Of Version

Version	Revise Date	Page	Content
1.0	2024-1-17	all	New released